



News Release

Unisem Reports Revenue of RM320.9 million (approx. US\$80.0 million) and Net Profit of RM37.8 million (approx. US\$9.4 million) for 2nd Quarter 2016

Kuala Lumpur, 5 August 2016 – Unisem (M) Berhad today announced results for the second quarter ended 30 June 2016 (**2Q16**).

Unisem recorded a consolidated revenue and net profit of RM320.9 million (approx. US\$80.0 million) and RM37.8 million (approx. US\$9.4 million) respectively for the quarter ended 30 June 2016. These represent improvement of 7.4 percent and 19.4 percent in revenue and net profit respectively against the corresponding quarter ended 30 June 2015 (**2Q15**).

For the six months period ended 30 June 2016, the Group recorded revenue and net profit of RM638.7 million (approx. US\$155.9 million) and RM73.0 million (approx. US\$17.8 million) respectively, these represent increase of 10.3 percent in revenue and 31.6 percent in net profit against the same period a year ago.

The increase in revenue for the financial year to date was mainly attributable to improved average selling prices arising from the appreciation of US\$/RM and US\$/RMB exchange rates, as compared to the rates that prevailed in the corresponding period a year ago. The improvement in net profit for the current financial year to date was due to increased revenue and improved margins from better contribution in our wafer bumping and advanced package operations.

Group earnings before interest, tax, depreciation and amortization (EBITDA) for 2Q16 came in at about RM84.7 million (approx. US\$21.1 million), EBITDA margin was about 26.4 percent. Equipment capacity utilization averaged at about 75 percent for the Group in 2Q16. Group capital expenditure incurred in 2Q16 was about RM27.6 million (approx. US\$6.9 million), principally for purchase of equipment for advanced packaging activities.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, the group managing director said, "We expect the performance of the Group to improve for the third financial quarter and remain satisfactory till the end of the financial year"

About Unisem

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. Unisem is an established MEMS OSAT with several years of experience in volume consumer and automotive production, in addition to a broad package portfolio covering multiple applications. The company has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China; and in Batam, Indonesia. Unisem is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com